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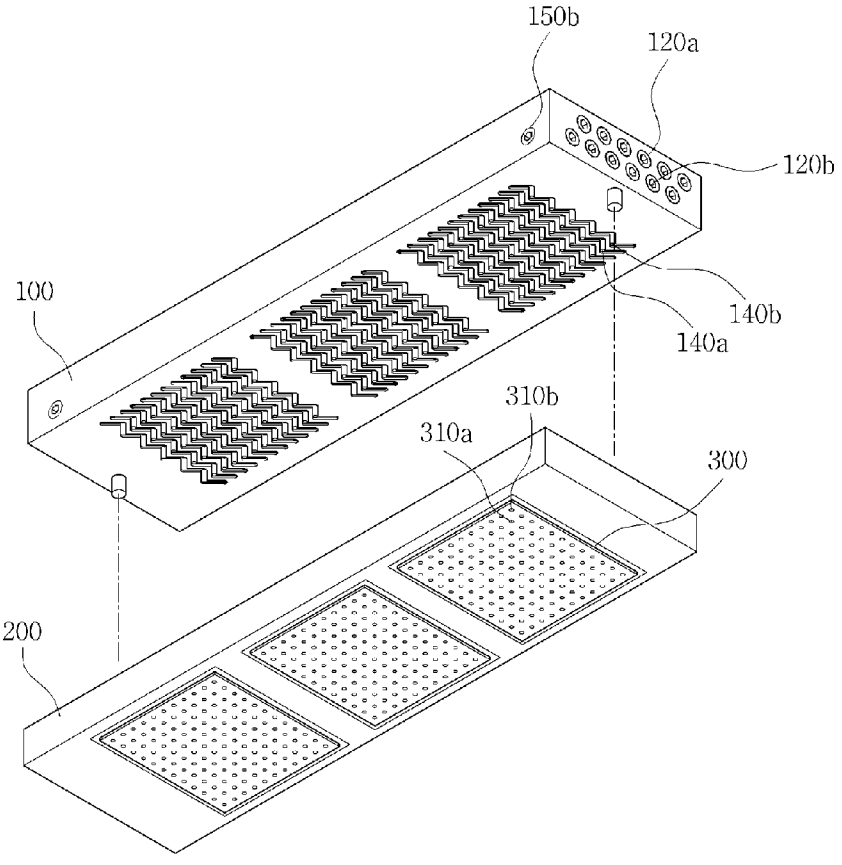
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(54) Title: SEMICONDUCTOR PACKAGE PICKUP APPARATUS



(57) Abstract: Disclosed is a semiconductor package pickup apparatus. The apparatus includes a picker base formed with first and second main feeding holes, which are connected to each pneumatic line providing a pneumatic pressure and aligned in a dual-layer structure, and an adsorption pad coupled to a lower portion of the picker base and formed with adsorption holes connected to the first and second main feeding holes. The pneumatic pressure supplied into the first and second main feeding holes is independently controlled, so that the apparatus easily loads or picks up semiconductor packages, even if the size of the semiconductor packages becomes reduced.

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